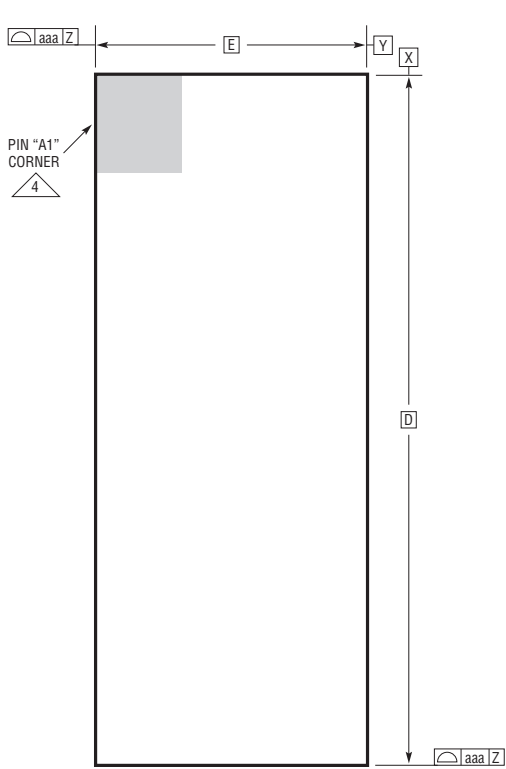
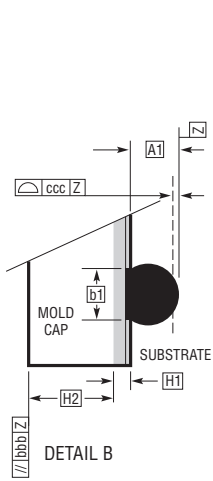


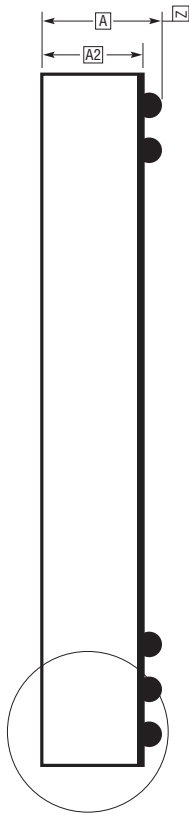
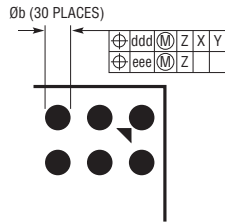
**BGA Package**  
**30-Lead (15mm × 6.25mm × 3.48mm)**  
 (Reference LTC DWG# 05-08-1580 Rev 0)



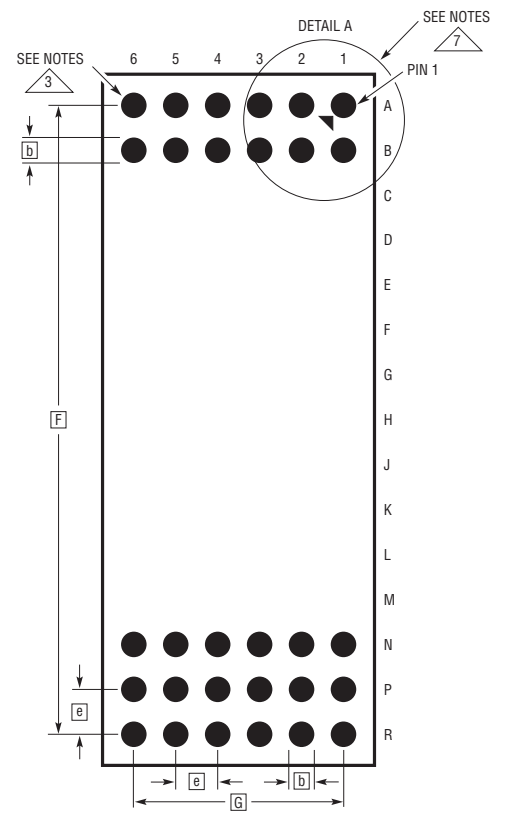
PACKAGE TOP VIEW



DETAIL A



DETAIL B  
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

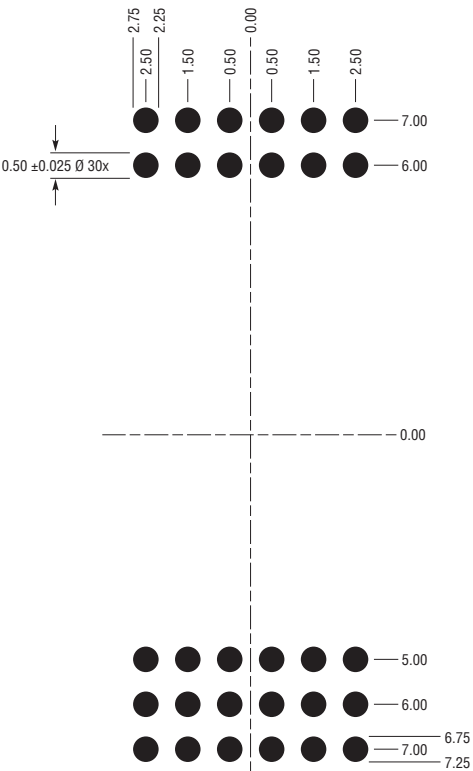
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

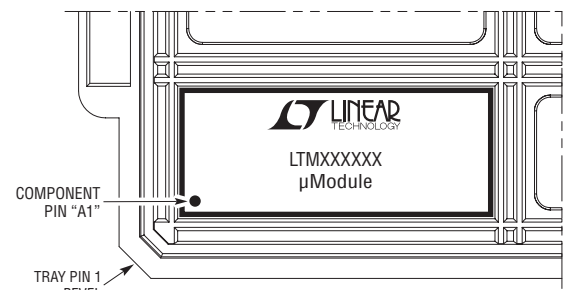
5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



SUGGESTED PCB LAYOUT  
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.28	3.48	3.68	
A1	0.40	0.50	0.60	BALL HT
A2	2.88	2.98	3.08	
b	0.45	0.60	0.75	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		15.00		
E		6.25		
e		1.00		
F		14.00		
G		5.00		
H1	0.43	0.48	0.53	SUBSTRATE THK
H2	2.45	2.50	2.55	MOLD CAP HT
aaa			0.15	
bbb			0.25	
ccc			0.15	
ddd			0.25	
eee			0.10	
TOTAL NUMBER OF BALLS: 30				



PACKAGE IN TRAY LOADING ORIENTATION